

HTB-100-HM170

- Medical Box PC
- Fanless Quad Core Box PC

New

Features

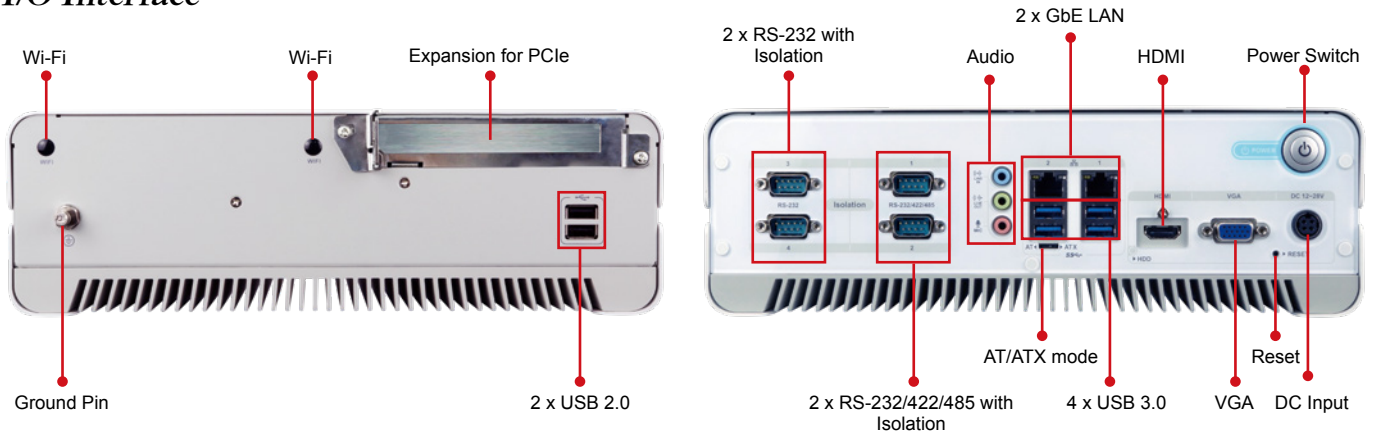
- Medical grade with high performance fanless embedded computing
- 6th Gen Intel® Core™ processor platform with Intel® HM170 chipset and DDR4 memory
- Triple independent display with high resolution support
- Isolated COM ports for enhancing safety among devices
- Optional PCIe x16 expansion slot supports more flexible functions



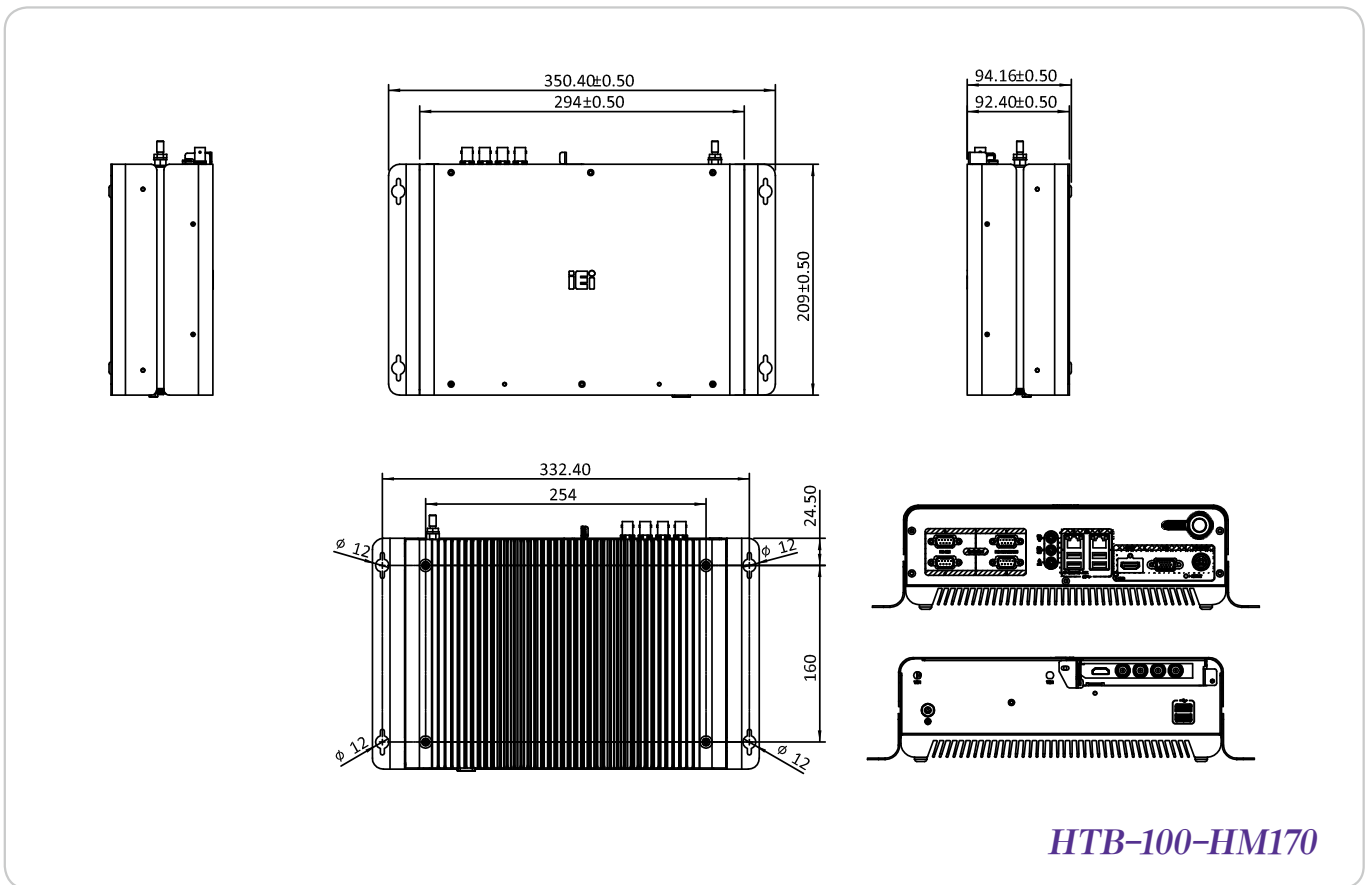
Specifications

Model	HTB-100-HM170	
Chassis	Color	Silver+Greyish blue
	Dimensions (WxDxH)	294 x 209 x 90.2
	System Fan	Fanless
	Chassis Construction	Extruded aluminum alloy
Motherboard	CPU	Intel® Core™ i7-6822EQ (2 GHz, quad-core, TDP=25) Intel® Core™ i5-6442EQ (1.9 GHz, quad-core, TDP=25)
	Chipset	Intel® HM170
	System Memory	2 x 260-pin DDR4 SO-DIMM, one 4 GB pre-installed (system max: 32GB)
Storage	Hard Drive	1 x 2.5" SATA 6Gb/s HDD/SSD bay
I/O Interfaces	USB 3.0	4
	USB 2.0	2
	Ethernet	2 x RJ-45 PCIe GbE by Intel® I211 controller
	COM Port	2 x RS-232 (DB-9, with 4 kV isolation) 2 x RS-232/422/485 (DB-9, with 4 kV isolation)
	Display	1 x VGA, 1 x HDMI 2.0, 1 x iDP (optional)
	Resolution	VGA: Up to 1920 x 1200@60HZ HDMI 2.0: Up to 4096 x 2160@60Hz
	Audio	Realtek ALC662, 5.1-channel High Definition Audio (HDA), Line-in, Line-out, Mic-in
	Wireless	1 x 802.11a/b/g/n/ac 2T2R (optional)
Expansions	PCIe	1 x PCIe x16
	PCIe Mini	1 x Half-size PCIe Mini 1 x Full-size PCIe Mini (supports mSATA, colay with SATA)
	M.2	1 x M.2 (A & E key)
Power	Power Input	DC Jack: 12~28V DC
	Power Consumption	19W@4.4A (Intel® Core™ i7-6822EQ with 4 GB memory)
Reliability	Mounting	Wall mounting
	Operating Temperature	0°C ~ 40°C with air flow (SSD), 10% ~ 95%, non-condensing
	Storage Temperature	-40°C ~ 70°C with air flow (SSD), 10% ~ 90%, non-condensing
	Operating Shock	Half-sine wave shock 5G; 11ms; 100 shocks per axis
	Operating Vibration	MIL-STD-810G 514.6 C-1 (with SSD)
	Safety / EMC	CE, FCC class B part 18, IEC 60601-1 V3.1, IEC 60601-1-2 V4.0, IEC 62304, ISO 14971
OS	Supported OS	Microsoft® Windows 8, Microsoft® Embedded Standard 7

I/O Interface



Dimensions (Unit: mm)



HTB-100-HM170

Ordering Information

Part No.	Description
HTB-100-HM170-i5/4G-R10	Ruggedized fanless embedded system with Intel® Core™ i5-6442EQ 1.9 GHz (up to 2.7 GHz, quad core, TDP 25W), 4GB DDR4 pre-installed memory, one PCIe x16 expansion, VGA/HDMI/iDP, COM port, 12~28V DC, RoHS
HTB-100-HM170-i7/4G-R10	Ruggedized fanless embedded system with Intel® Core™ i7-6822EQ 2.0 GHz (up to 2.8 GHz, quad core, TDP 25W), 4GB DDR4 pre-installed memory, one PCIe x16 expansion, VGA/HDMI/iDP, COM port, 12~28V DC, RoHS

Options

Part No.	Description
63040-580120-000-RS	Adapter Power, Darfon, H1120-B0, BK.1HB2J3001, Active PFC, Vin:90~264VAC, 120W, 1200mm, MEDICAL, Vout:19VDC, Din 4Pin/lock, CCL, RoHS
32702-000200-100-RS	POWER CORD;EUROPEAN CODE(VDE)

Packing List

1 x Utility CD	1 x Chassis Screw	1 x One Key Recovery CD	1 x Mounting Bracket
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